

COMPLEMENTARY 20V LOW SATURATION TRANSISTORS

Features

NPN Transistor

- $BV_{CEO} > 20V$
- $I_C = 4.5A$ Continuous Collector Current
- Low Saturation Voltage (150mV max @ 1A)
- $R_{SAT} = 47m\Omega$ for a low equivalent On-Resistance

PNP Transistor

- $BV_{CEO} > -20V$
- $I_C = -3.5A$ Continuous Collector Current
- Low Saturation Voltage (-220mV max @ -1A)
- $R_{SAT} = 64m\Omega$ for a low equivalent On-Resistance

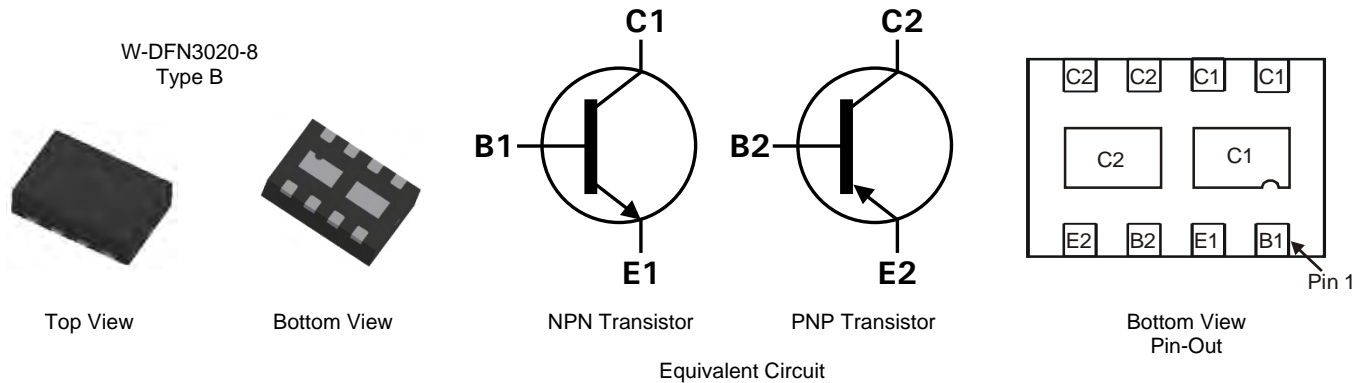
- h_{FE} characterized up to 6A for high current gain hold up
- Low profile 0.8mm high package for thin applications
- $R_{\theta JA}$ efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP capable (Note 4)**

Mechanical Data

- Case: W-DFN3020-8 Type B
- Nominal package height: 0.8mm
- Case material: molded plastic. "Green" molding compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu, Solderable per MIL-STD-202, Method 208
- Weight: 0.013 grams (approximate)

Applications

- DC – DC Converters
- Charging circuits
- Power switches
- Motor control
- LED Backlighting circuits
- Portable applications



Ordering Information (Note 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC6718MCTA	AEC-Q101	DB2	7	8	3,000
ZXTC6718MCQTA	Automotive	DB2	7	8	3,000

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
 5. For packaging details, go to our website at <http://www.diodes.com>

Marking Information



DB2 = Product type marking code
Top view, dot denotes pin 1

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

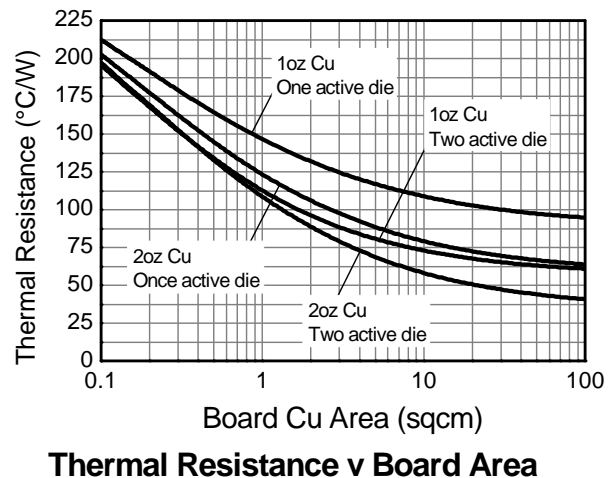
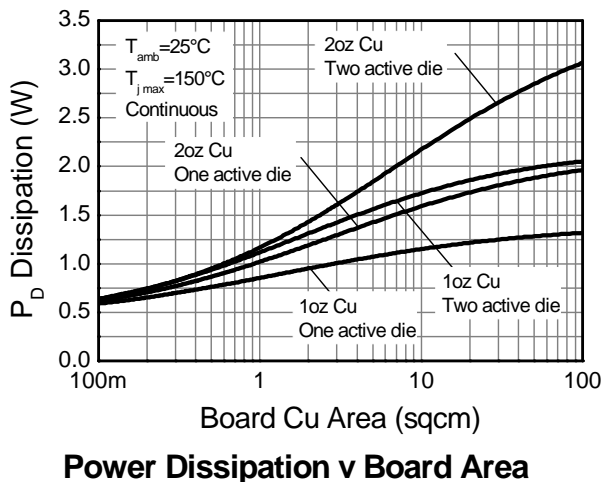
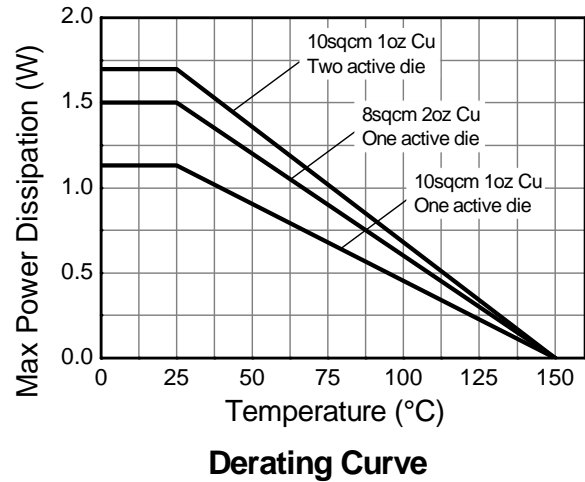
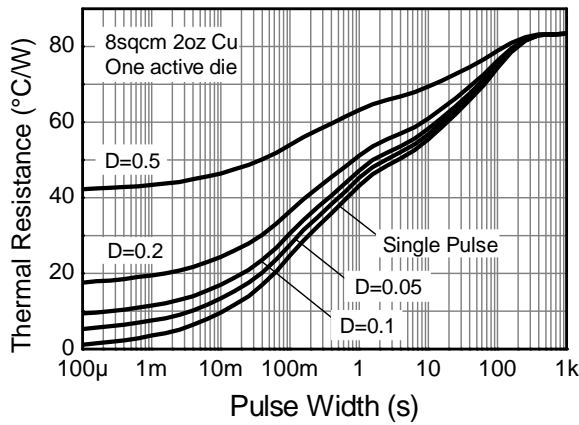
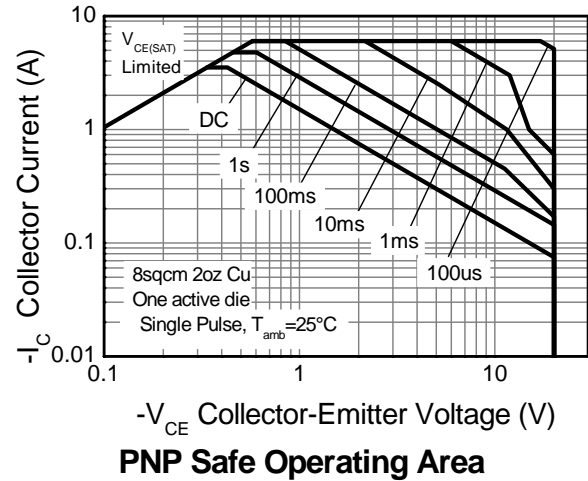
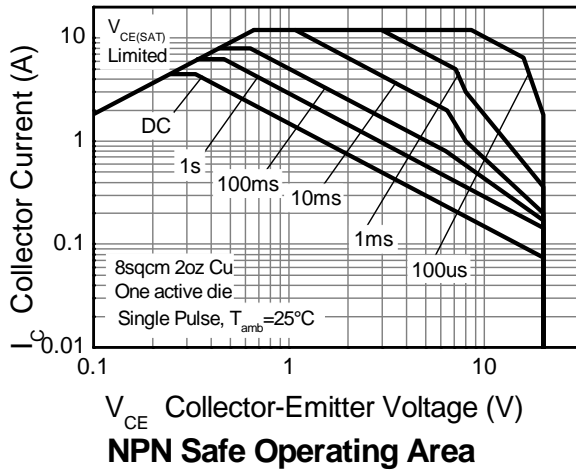
Characteristic	Symbol	NPN	PNP	Unit
Collector-Base Voltage	V _{CB0}	40	-25	V
Collector-Emitter Voltage	V _{CEO}	20	-20	V
Emitter-Base Voltage	V _{EBO}	7	-7	V
Peak Pulse Current	I _{CM}	12	-6	A
Continuous Collector Current	I _C	4.5	-3.5	A
Continuous Collector Current		5	-3.8	
Base Current	I _B	1		A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit
Power Dissipation Linear Derating Factor	P _D	1.5		W
		12		
		2.45		
		19.6		
		1.13		
Thermal Resistance, Junction to Ambient	R _{θJA}	8		°C/W
		1.7		
		13.6		
		83.3		
Thermal Resistance, Junction to Lead	R _{θJL}	51.0		°C/W
		111		
		73.5		
		17.1		
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150		°C

- Notes:
6. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.
 7. Same as note (6), except the device is measured at t < 5 sec.
 8. Same as note (6), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.
 9. For a dual device with one active die.
 10. For dual device with 2 active die running at equal power.
 11. Thermal resistance from junction to solder-point (on the exposed collector pads).

Thermal Characteristics and Derating Information

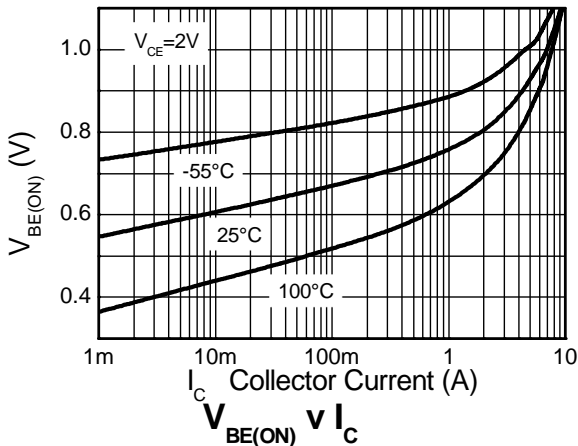
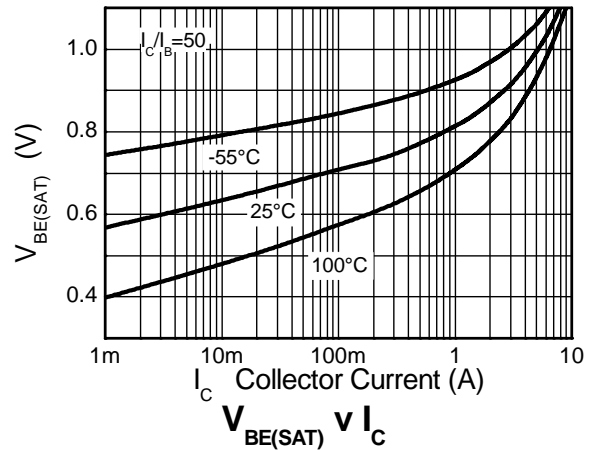
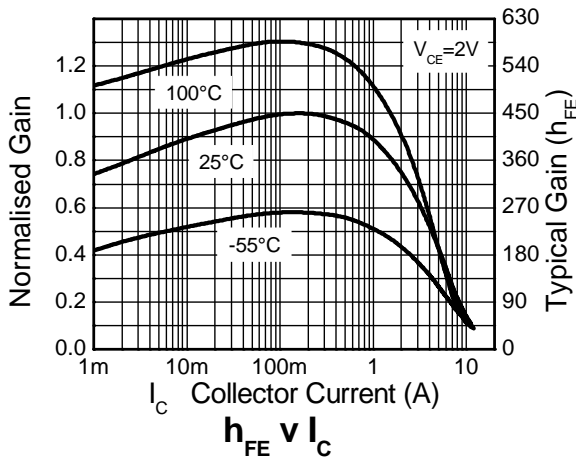
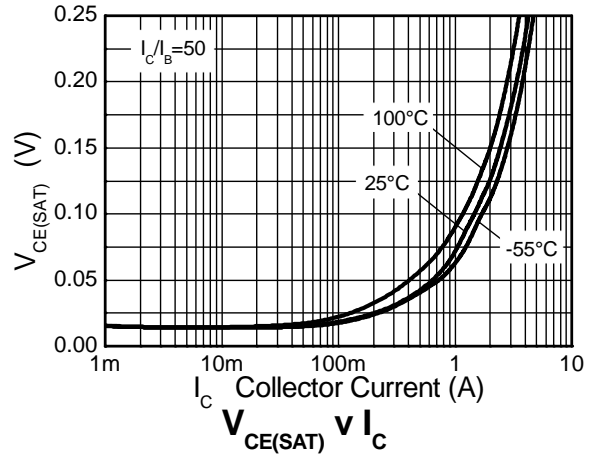
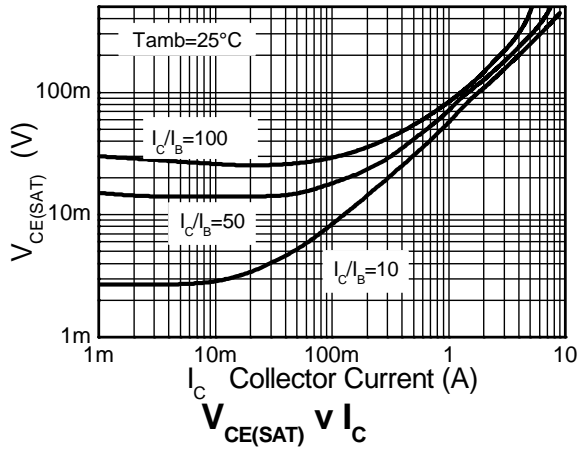


NPN - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	40	100	-	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	20	27	-	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.2	-	V	I _E = 100μA
Collector Cutoff Current	I _{CBO}	-	-	100	nA	V _{CB} = 30V
Emitter Cutoff Current	I _{EBO}	-	-	100	nA	V _{EB} = 6V
Collector Emitter Cutoff Current	I _{CES}	-	-	100	nA	V _{CE} = 16V
Static Forward Current Transfer Ratio (Note 12)	h _{FE}	200	400	-	-	I _C = 10mA, V _{CE} = 2V
		300	450	-	-	I _C = 200mA, V _{CE} = 2V
		200	360	-	-	I _C = 2A, V _{CE} = 2V
		100	180	-	-	I _C = 6A, V _{CE} = 2V
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}	-	8	15	mV	I _C = 0.1A, I _B = 10mA
		-	90	150		I _C = 1A, I _B = 10mA
		-	115	135		I _C = 2A, I _B = 50mA
		-	190	250		I _C = 3A, I _B = 100mA
		-	210	300		I _C = 4.5A, I _B = 125mA
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	-	0.88	0.97	V	I _C = 4.5A, V _{CE} = 2V
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	0.98	1.07	V	I _C = 4.5A, I _B = 125mA
Output Capacitance	C _{obo}	-	23	30	pF	V _{CB} = 10V, f = 1MHz
Transition Frequency	f _T	100	140	-	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz
Turn-on Time	t _{on}	-	170	-	ns	V _{CC} = 10V, I _C = 3A
Turn-off Time	t _{off}	-	400	-	ns	I _{B1} = I _{B2} = 10mA

Notes: 12. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

NPN - Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

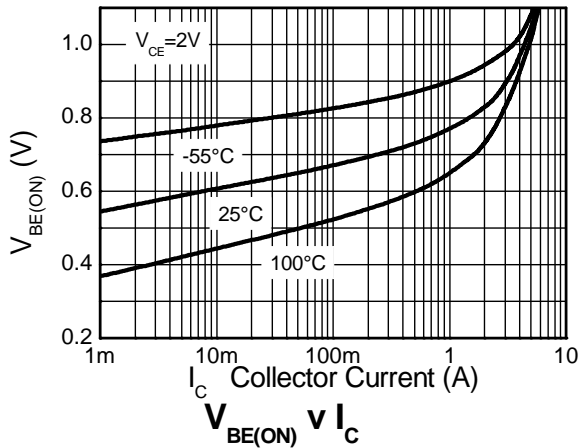
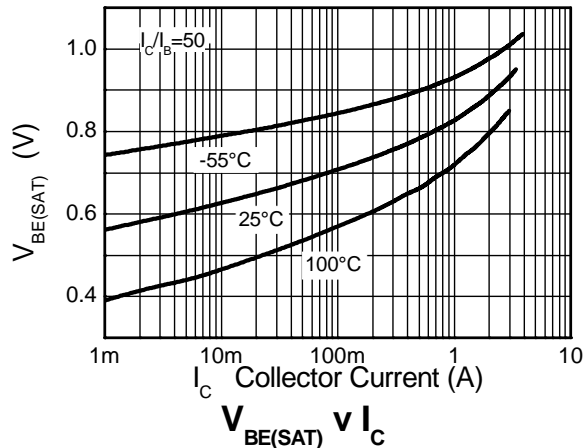
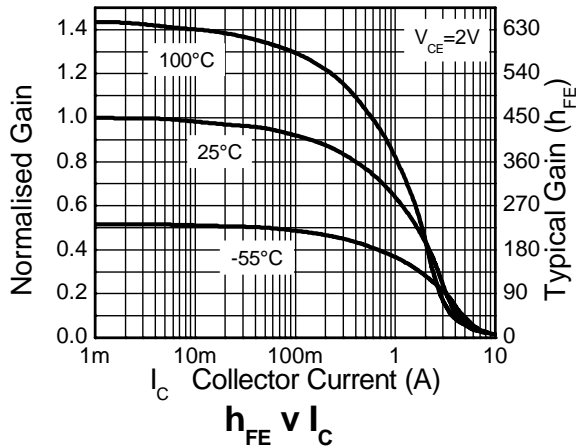
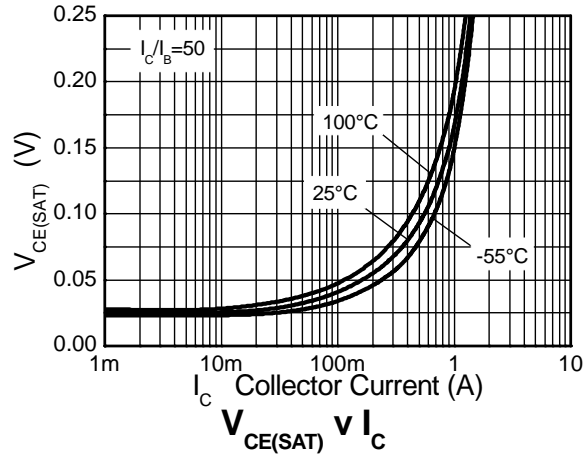
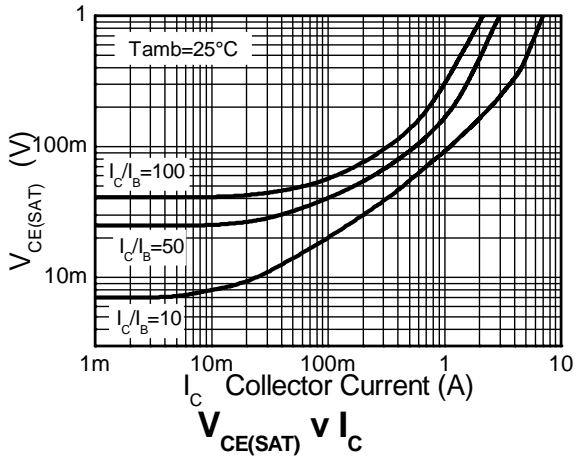


PNP - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-25	-35	-	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	-20	-25	-	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	-8.5	-	V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	-	-	-100	nA	V _{CB} = -20V
Emitter Cutoff Current	I _{EBO}	-	-	-100	nA	V _{EB} = -6V
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CES} = -16V
Static Forward Current Transfer Ratio (Note 12)	h _{FE}	300 300 150 15	475 450 230 30	- - - -	-	I _C = -10mA, V _{CE} = -2V I _C = -100mA, V _{CE} = -2V I _C = -2A, V _{CE} = -2V I _C = -6A, V _{CE} = -2V
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(sat)}	- - - - -	-19 -170 -190 -240 -225	-30 -220 -250 -350 -300	mV	I _C = -0.1A, I _B = -10mA I _C = -1A, I _B = -20mA I _C = -1.5A, I _B = -50mA I _C = -2.5A, I _B = -150mA I _C = -3.5A, I _B = -350mA
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(on)}	-	-0.87	-0.95	V	I _C = -3.5A, V _{CE} = -2V
Base-Emitter Saturation Voltage (Note 12)	V _{BE(sat)}	-	-1.01	-1.12	V	I _C = -3.5A, I _B = -350mA
Output Capacitance	C _{obo}	-	21	30	pF	V _{CB} = -10V, f = 1MHz
Transition Frequency	f _T	150	180	-	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Turn-on Time	t _{on}	-	40	-	ns	V _{CC} = -10V, I _C = -1A
Turn-off Time	t _{off}	-	670	-	ns	I _{B1} = I _{B2} = -10mA

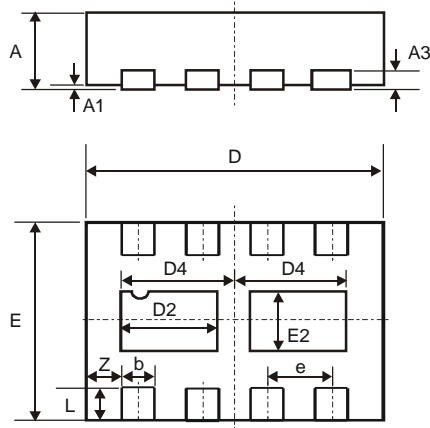
Notes: 12. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

PNP - Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

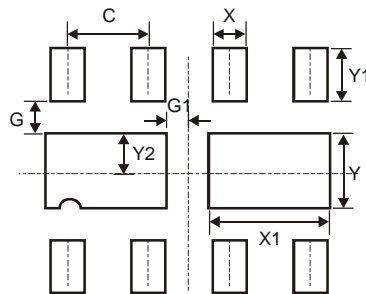
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



W-DFN3020-8 Type B			
Dim	Min	Max	Typ
A	0.77	0.83	0.80
A1	0	0.05	0.02
A3	-	-	0.15
b	0.25	0.35	0.30
D	2.95	3.075	3.00
D2	0.82	1.02	0.92
D4	1.01	1.21	1.11
e	-	-	0.65
E	1.95	2.075	2.00
E2	0.43	0.63	0.53
L	0.25	0.35	0.30
Z	-	-	0.375
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.650
G	0.285
G1	0.090
X	0.400
X1	1.120
Y	0.730
Y1	0.500
Y2	0.365

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